

REVERSE ENGINEERING CHALLENGE

VRC MIDDLE SCHOOL 2023/2024

D-Link DIR-605L

Team 96944X

Author :

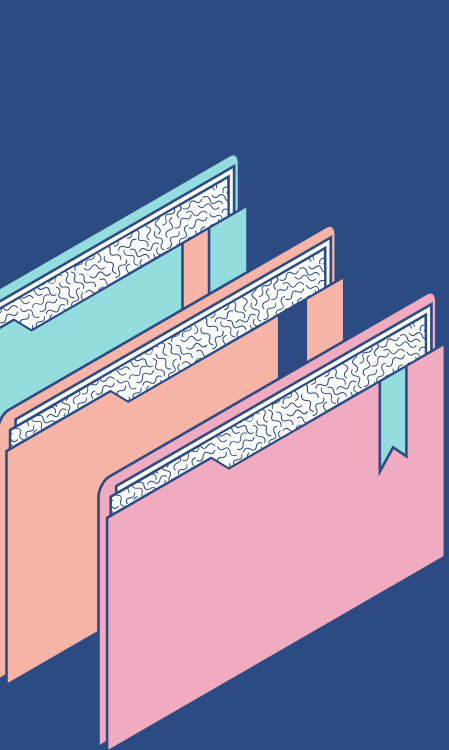
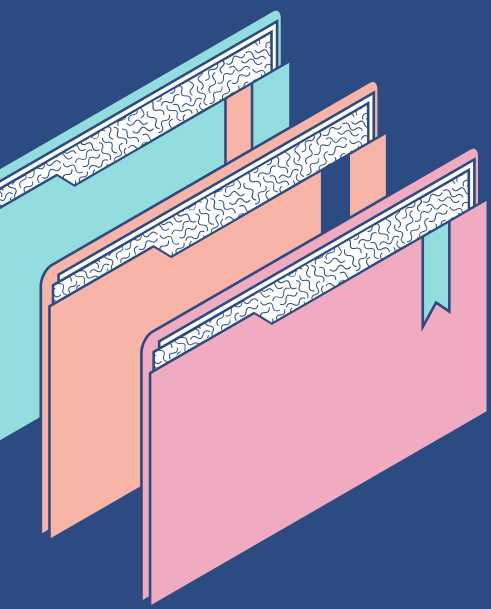
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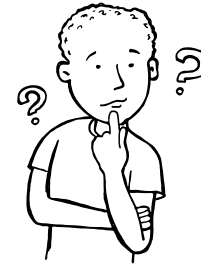


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Why the D-Link DIR-605L ?



In the process of making VEX robots, we constantly need to discuss with team members and consult relevant information, such as competition rules and mechanical structures, all of which are closely related to the internet.

During this process, we began to ponder how a router can provide us with wireless network connectivity through a single network cable, and what its internal structure is. Does the direction and size of the antenna really affect the network signal?

Considering the above questions, we decided to use the D-Link DIR-650L as our research project. We disassemble it and try to understand its principles and architecture, so that we not only know how to use the network, but also learn to understand the knowledge and principles behind it.



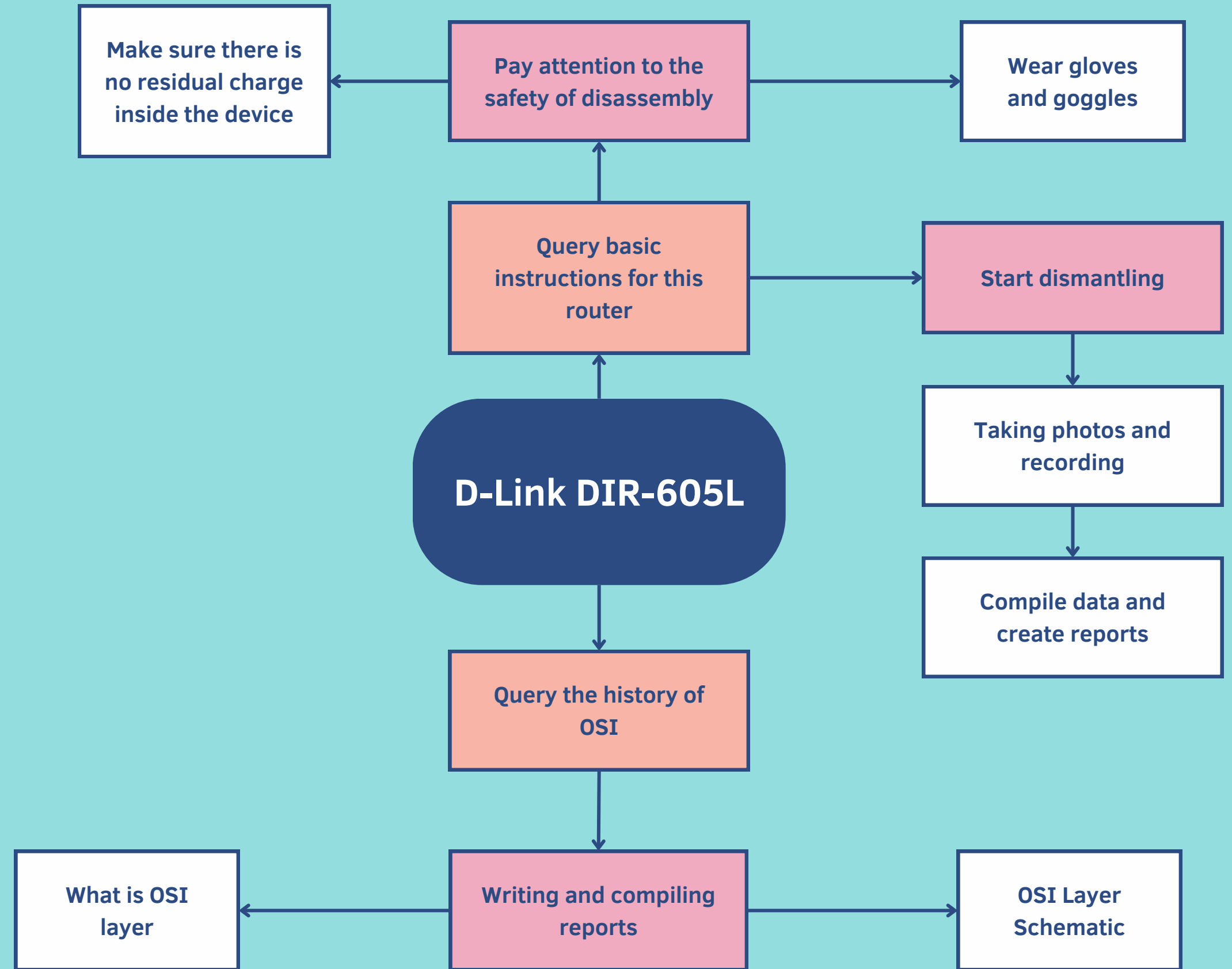
**D-Link DIR-605L
Front view**



**D-Link DIR-605L
Rear view**

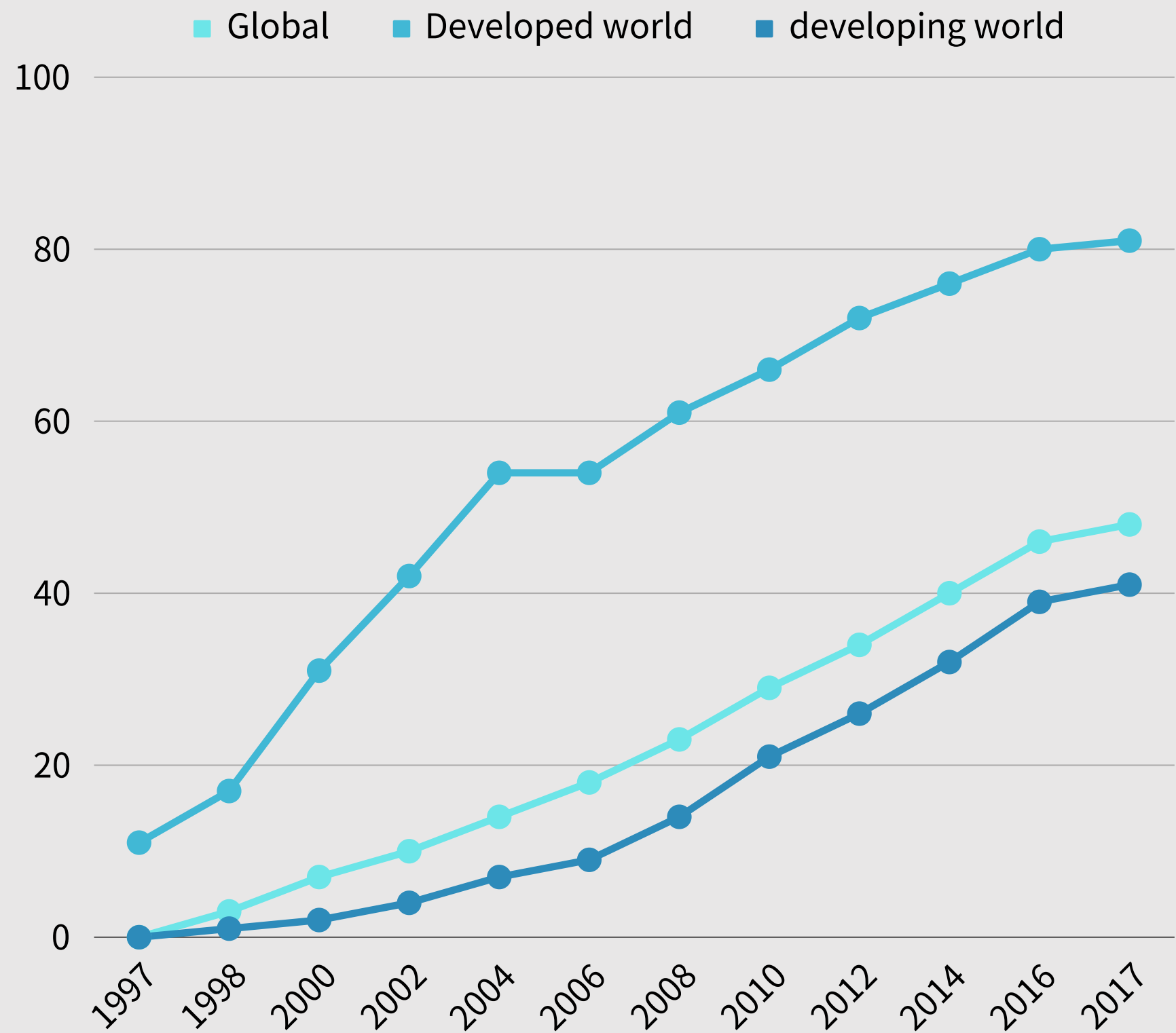
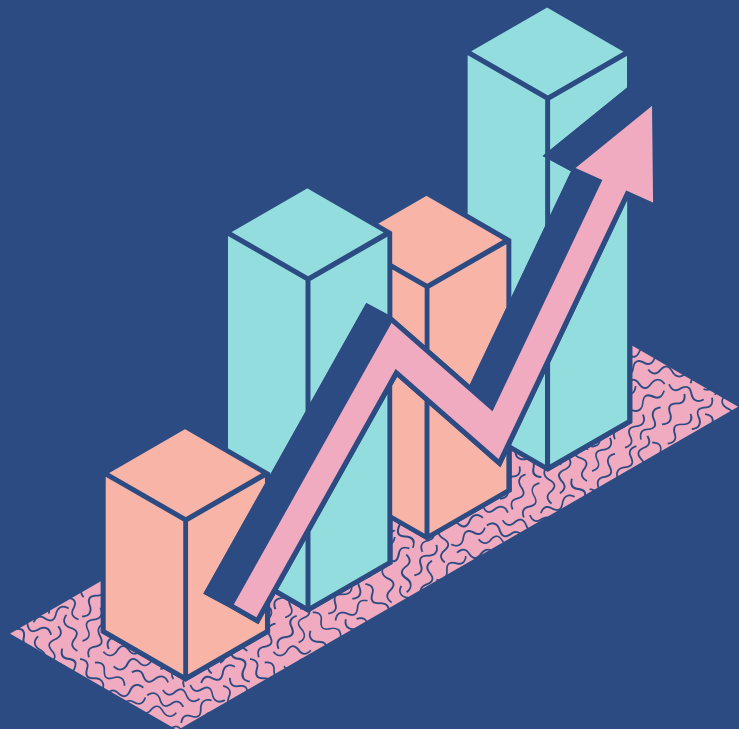
Flow diagram

Through thorough pre-planning of the disassembly process and division of tasks, we can avoid situations where recording is forgotten during actual operations. This approach also enhances teamwork and efficiency.



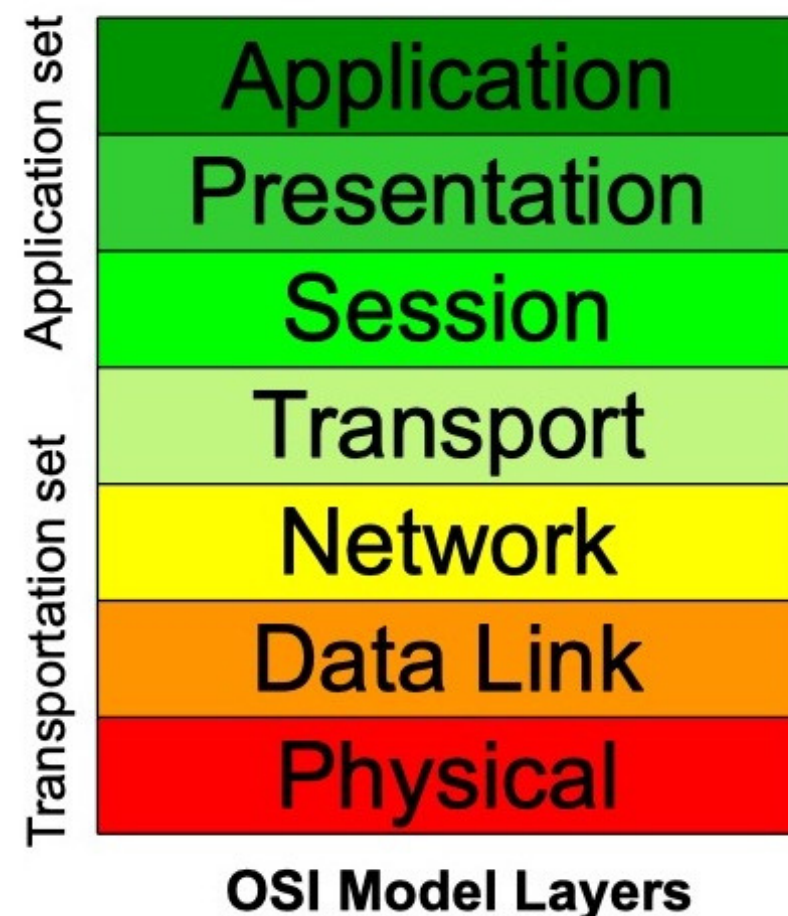
Internet users per 100 inhabitants

We can know from the data that people's demand for the Internet is gradually increasing



What is OSI layer ?

The OSI model is a conceptual framework that is referenced in the development of network standards. The OSI model is divided into seven different levels.



Top layer

7. Application Layer

The main function of the application layer is to process applications.

6. Presentation Layer

Convertible presentation through display layer.

5. Session Layer

This level is responsible for establishing network connections.

4. Transport Layer

The transmission layer is mainly responsible for the overall data transmission and control of the computer.

3. Network Layer

Definition Network Routing and Addressing Functions.

2. Data Link Layer

The main purpose is to create logical links between networks.

1. Physical Layer

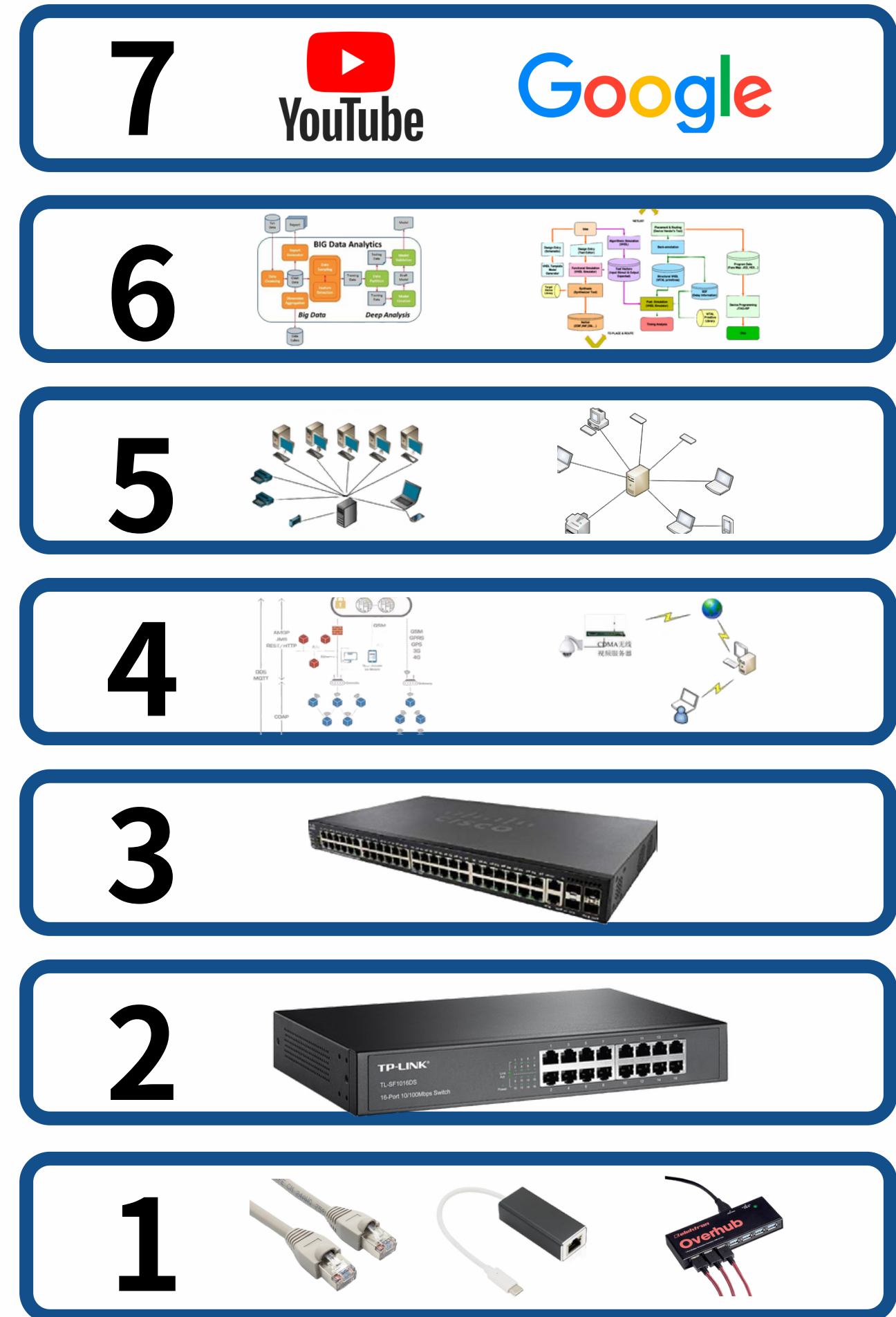
Used to define the transfer of bit data between networked devices.

Bottom Layer

OSI Layer Schematic

Each layer in the OSI model performs specific functions, and communication between layers is achieved through standardized protocols and interfaces. This modular approach to networking allows for interoperability between different systems and technologies.

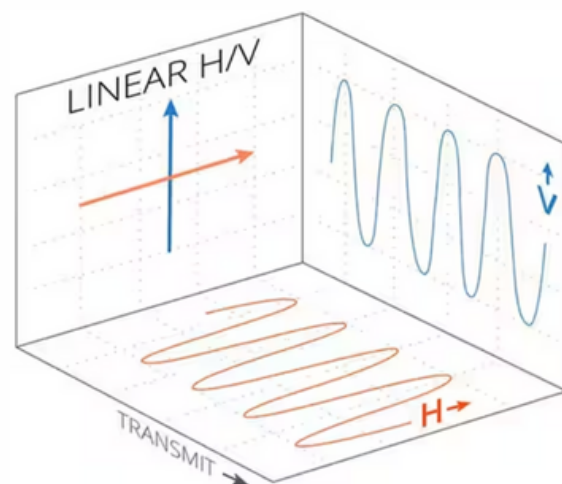
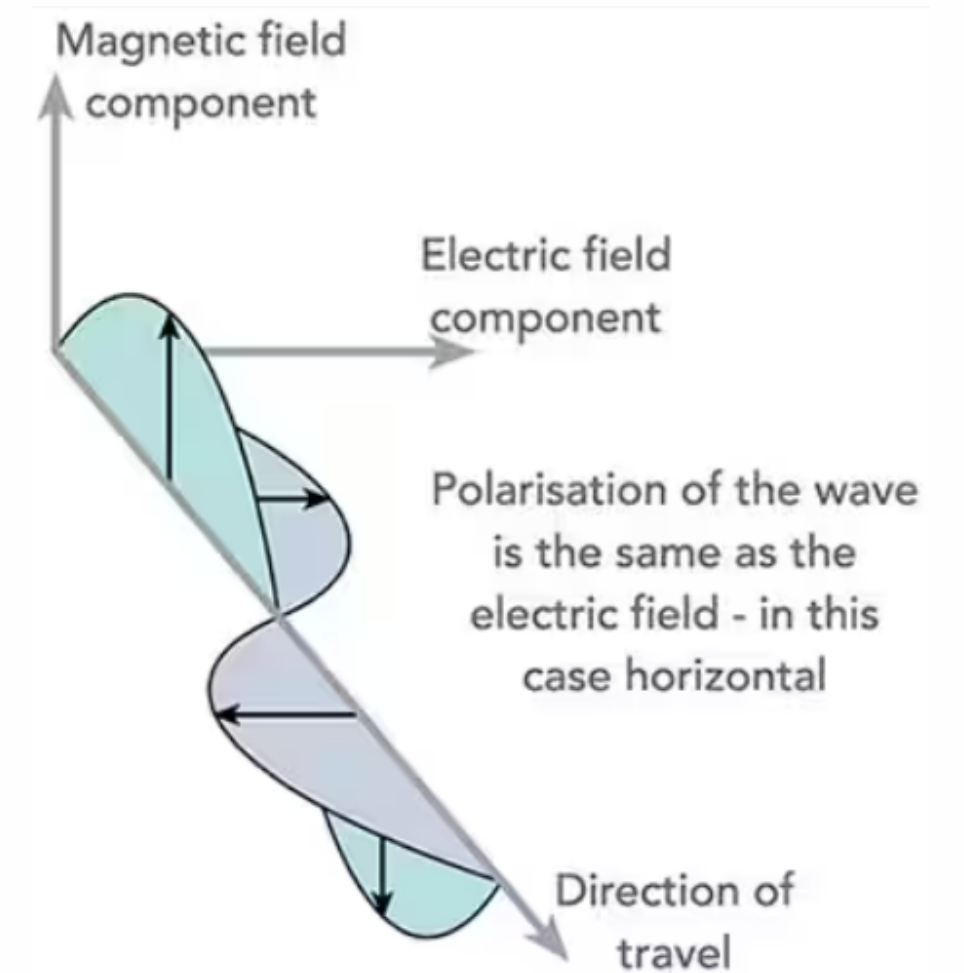
OSI model		
Layer	Name	Example protocols
7	Application Layer	HTTP, FTP, DNS, SNMP, Telnet
6	Presentation Layer	SSL, TLS
5	Session Layer	NetBIOS, PPTP
4	Transport Layer	TCP, UDP
3	Network Layer	IP, ARP, ICMP, IPSec
2	Data Link Layer	PPP, ATM, Ethernet
1	Physical Layer	Ethernet, USB, Bluetooth, IEEE802.11



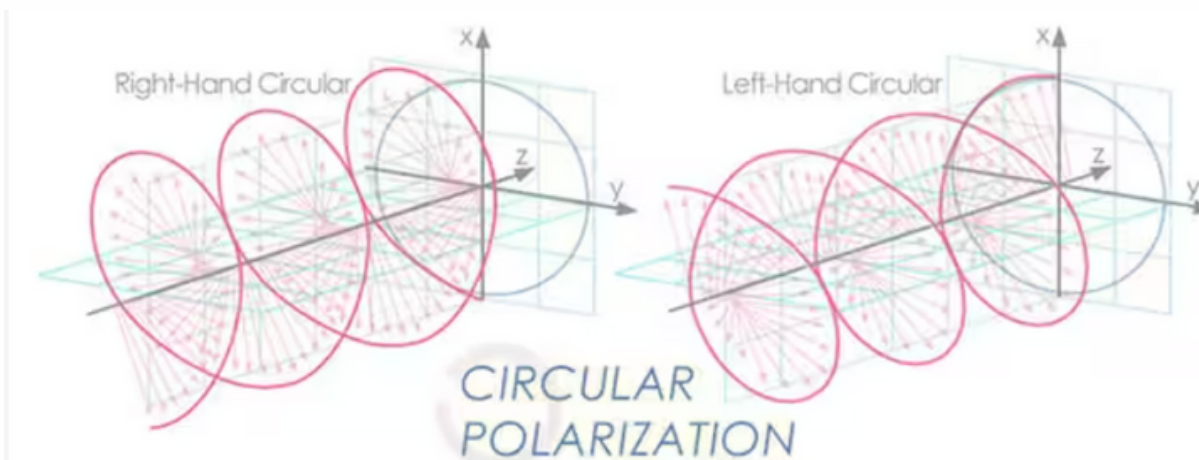
Antenna polarization

These waves consist of electric and magnetic fields traveling in a single direction. The electric and magnetic fields are perpendicular to each other, as well as perpendicular to the direction of propagation of the plane wave.

Polarization refers to the plane of the electric field as viewed from the signal transmitter: in horizontal polarization, the electric field oscillates horizontally, whereas in vertical polarization, the electric field oscillates vertically.



Linear polarization provides two orthogonal polarization options.



In circular polarization, the electric field vector of the electromagnetic wave rotates; this rotation can be either right-handed or left-handed.

Disassembly process



D-Link DIR-605L
Front view



D-Link DIR-605L
Rear view

Precautions



- 1 ‣ Disassemble the equipment while ensuring that it is powered off.
- 2 ‣ Confirm that there are no residual charges inside the capacitors.
- 3 ‣ Wear safety goggles and gloves when disassembling the casing.

1



The manufacturer hides the screws under the cushion for aesthetic reasons.

2



So we're going to remove the pads and then find the screws and remove them.

3



Separate host and cover.

4



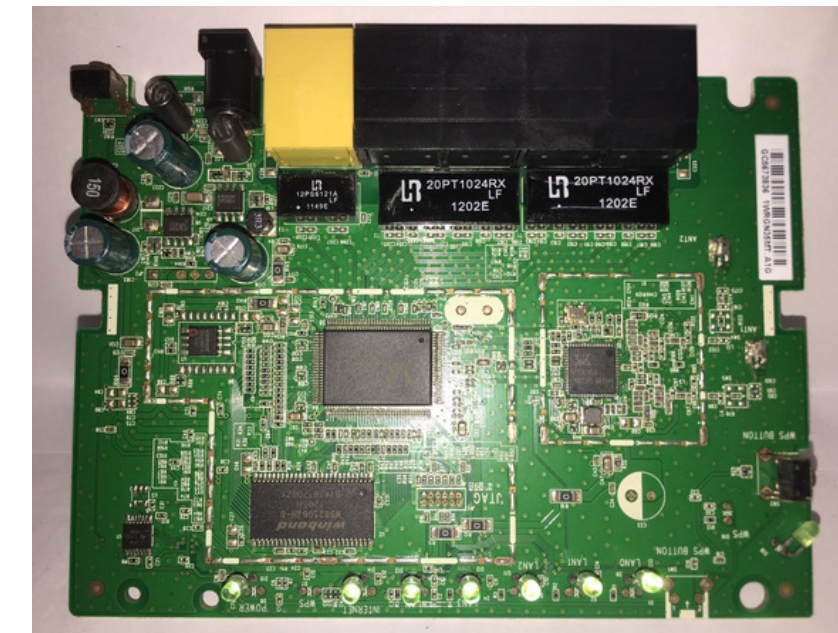
we remove the cushion first, then we will find the screws and remove them.

5



After removing the screws, we separate the cover from the main body of the host.

6



Internal host circuit board

7



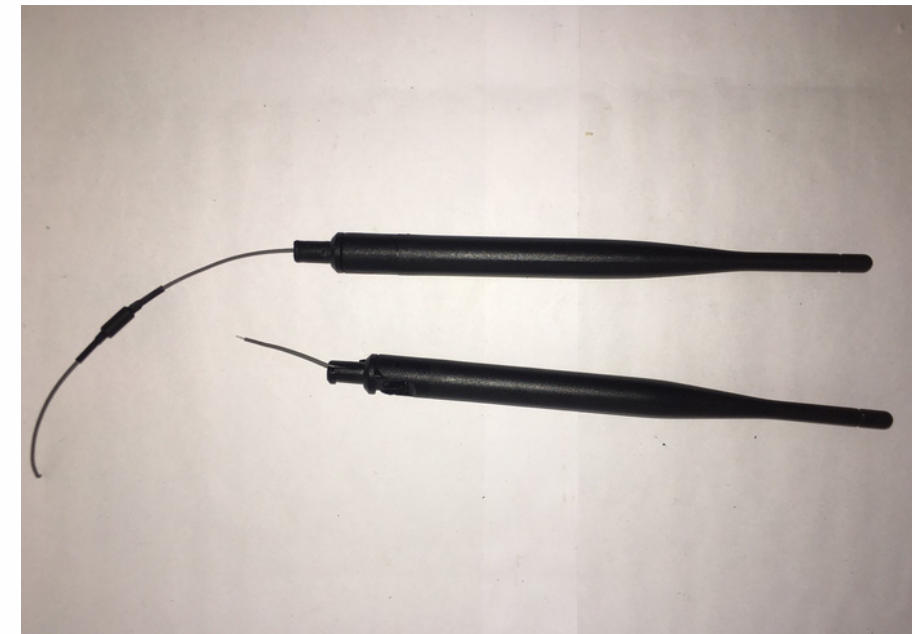
Enclosure after removing the Internal host circuit.

8



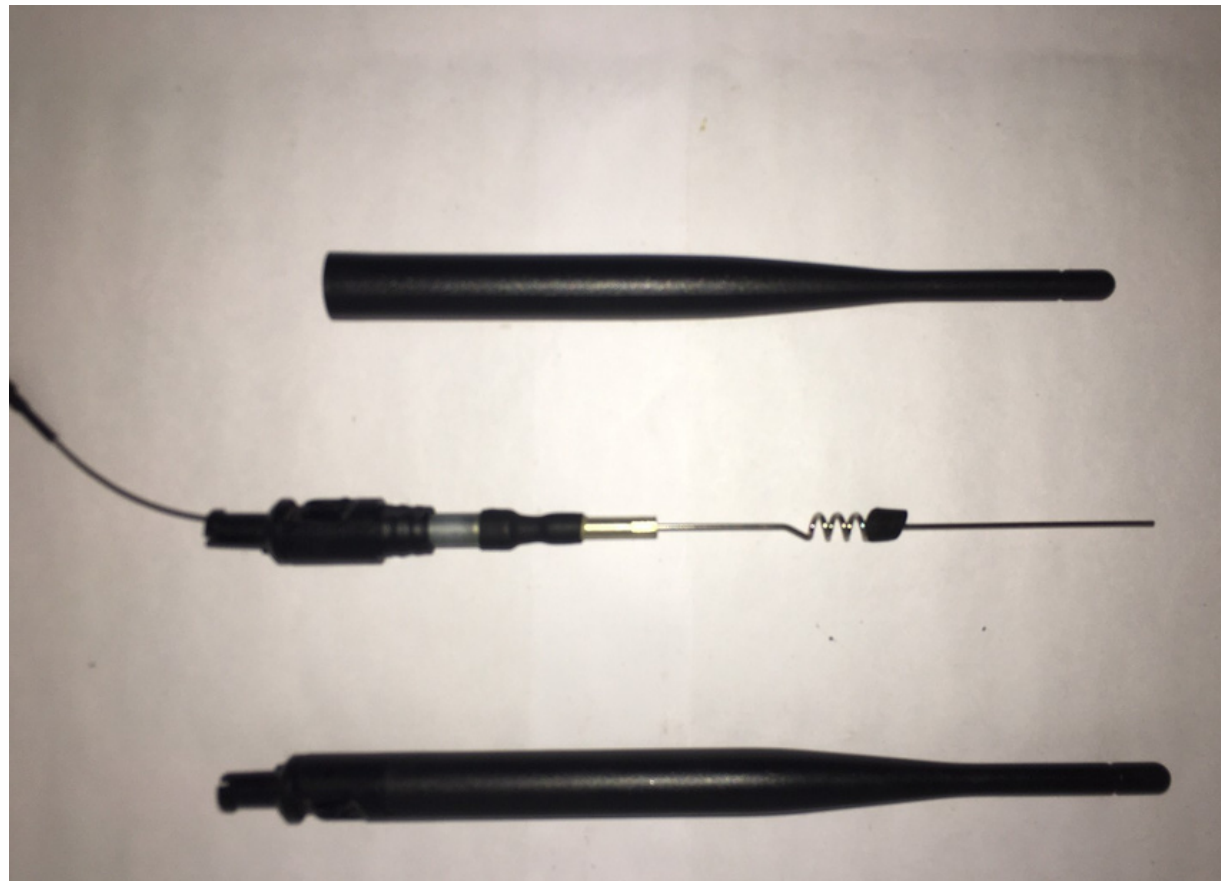
After removing the cover and internal host circuit board, you can clearly see the antenna inside.

9



We removed the antenna from the chassis.

10



Then remove the housing from the antenna.

11



All dismantled parts.

RT8292AHZSP

High-efficiency current mode synchronous step-down regulator that can deliver up to 2A output current from a wide input voltage range of 4.5V to 23V



12PS6121A

Designed to meet IEEE 802.3u requirement, including 350uH OCL with 8mA bias.



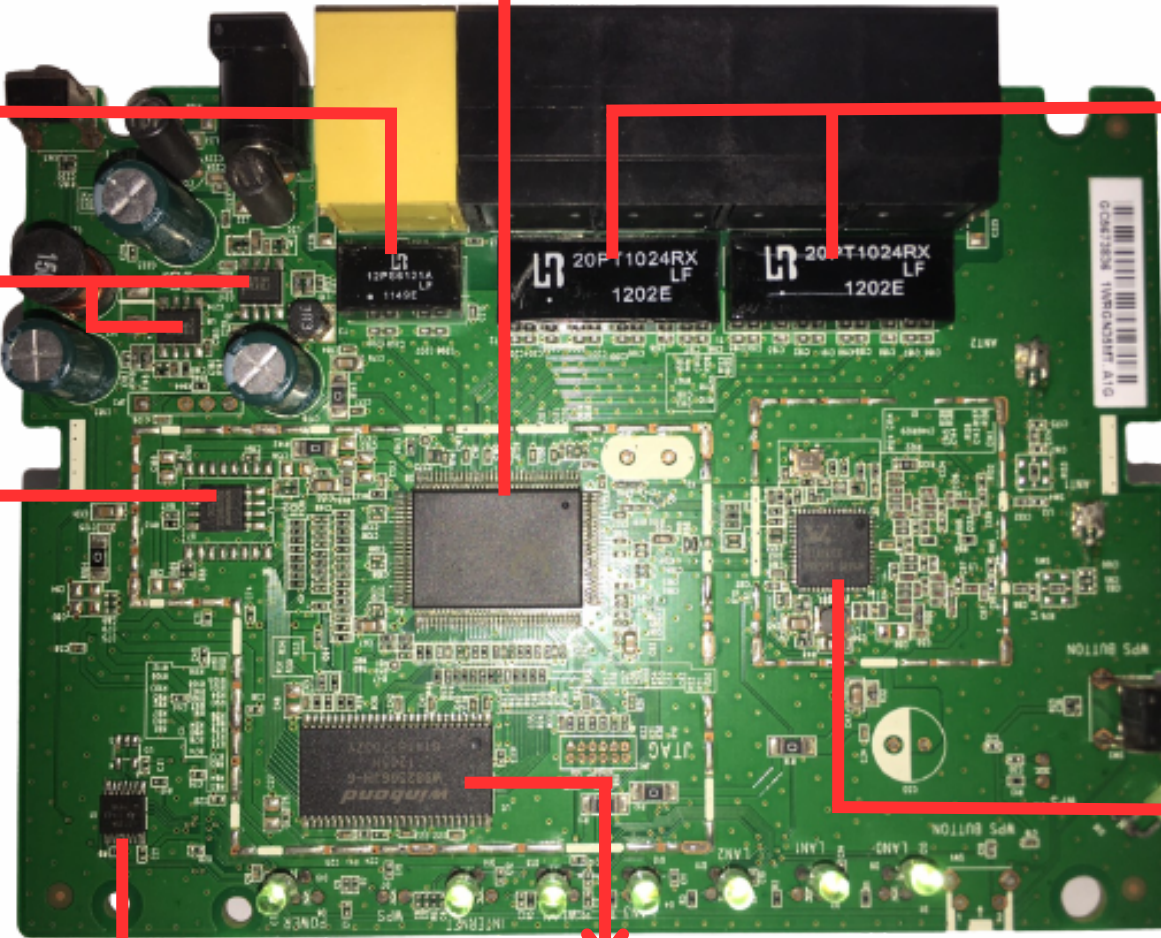
RTL8196C

Realtek provides the turnkey solution for 11n Router/AP in hardware and software.



20PT1024RX-LF

Compliant with IEEE 802.3u and ANSI X3.263 standards including 350uH OCL with 8mA Bias. | Symmetrical TX and RX channels for Auto MDI/MDIX capability.



W25Q32BV

3V 32M-BIT SERIAL FLASH MEMORY WITH DUAL AND QUAD SPI

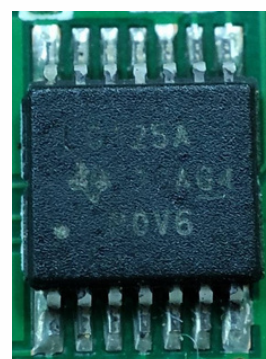


RTL8192CE

SINGLE-CHIP IEEE 802.11b/g/n 2T2R WLAN CONTROLLER w/PCI EXPRESS INTERFACE



lc125a


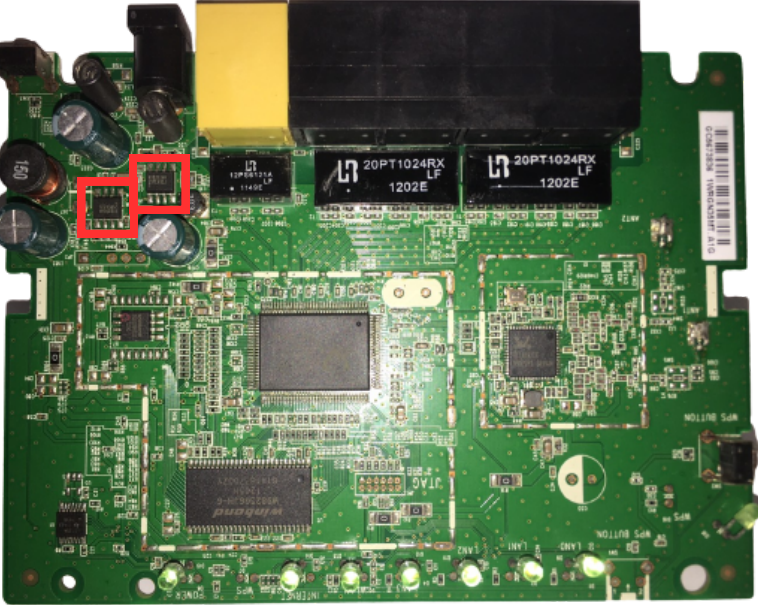

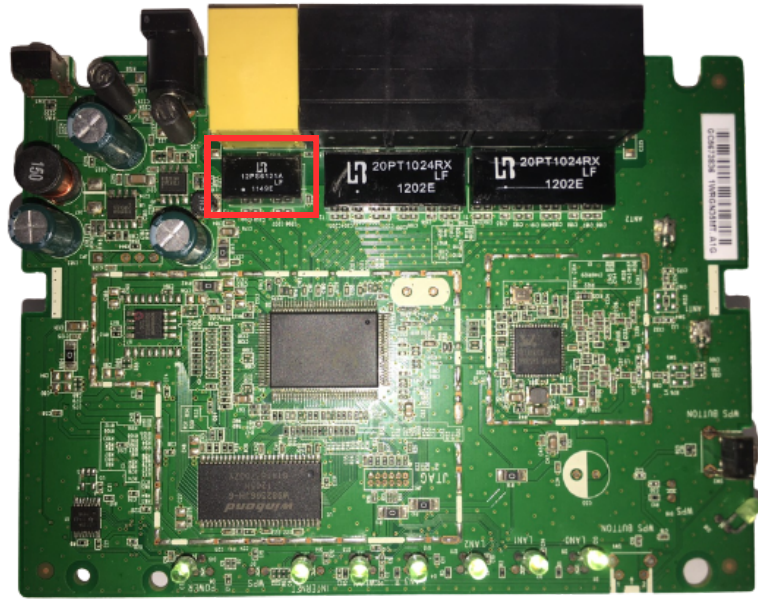


W9825G6JH

4M X 4 BANKS X 16 BITS SDRAM

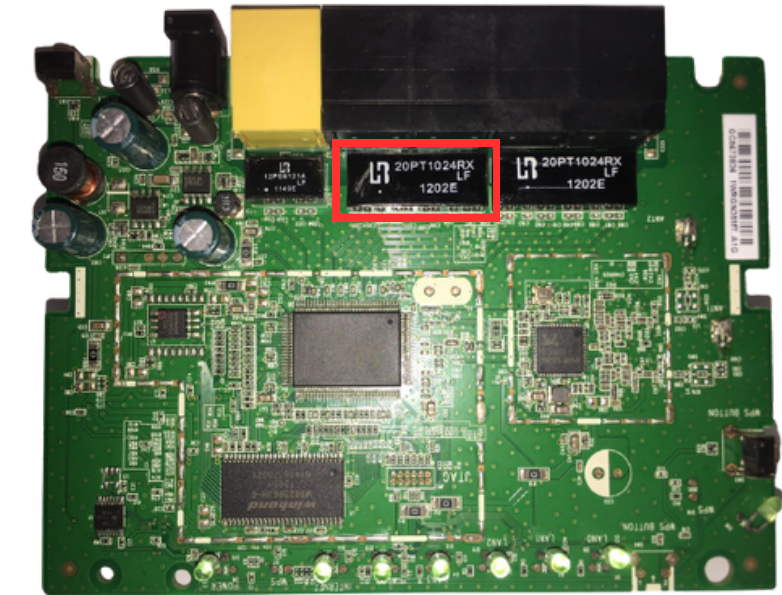


Part Name and Function

<p>RT8292AHZSP</p>	<p>High-efficiency current mode synchronous step-down regulator that can deliver up to 2A output current from a wide input voltage range of 4.5V to 23V</p>	 <p>A close-up photograph of the RT8292AHZSP integrated circuit. The chip is a dark, square component with eight pins, mounted on a green printed circuit board. The text "RT8292AH" and "ZSPEA92J" is printed on the top surface of the chip.</p>	 <p>A photograph of a green printed circuit board (PCB) populated with various electronic components. A red rectangular box highlights the RT8292AHZSP chip, which is located in the upper-left quadrant of the board. Other components visible include capacitors, inductors, and other integrated circuits.</p>
<p>12PS6121A</p>	<p>Designed to meet IEEE 802.3u requirement, including 350uH OCL with 8mA bias.</p>	 <p>A close-up photograph of the 12PS6121A integrated circuit. The chip is a dark, rectangular component with a white label that reads "12PS6121A LF" and "1149E". It is mounted on a green PCB.</p>	 <p>A photograph of a green printed circuit board (PCB) populated with various electronic components. A red rectangular box highlights the 12PS6121A chip, which is located in the upper-left quadrant of the board. Other components visible include capacitors, inductors, and other integrated circuits.</p>

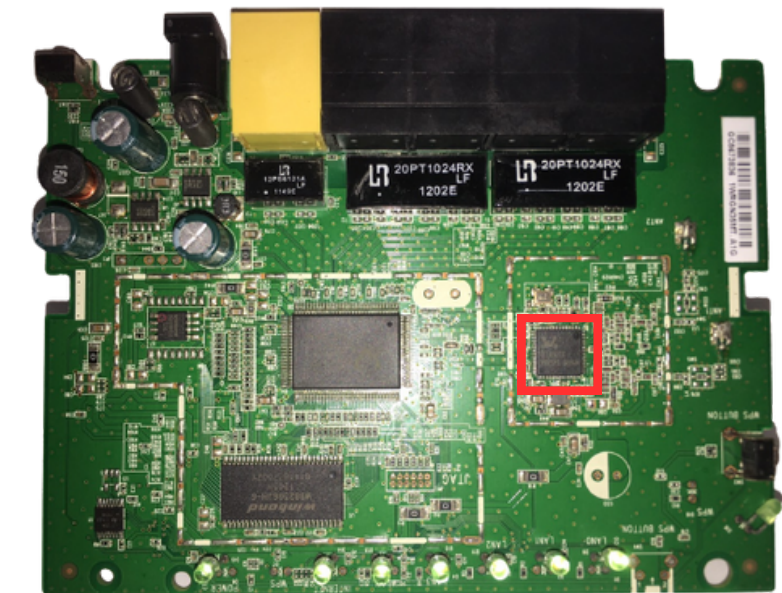
20PT1024RX-
LF

Realtek provides the turnkey
solution for 11n Router/AP in
hardware and software.



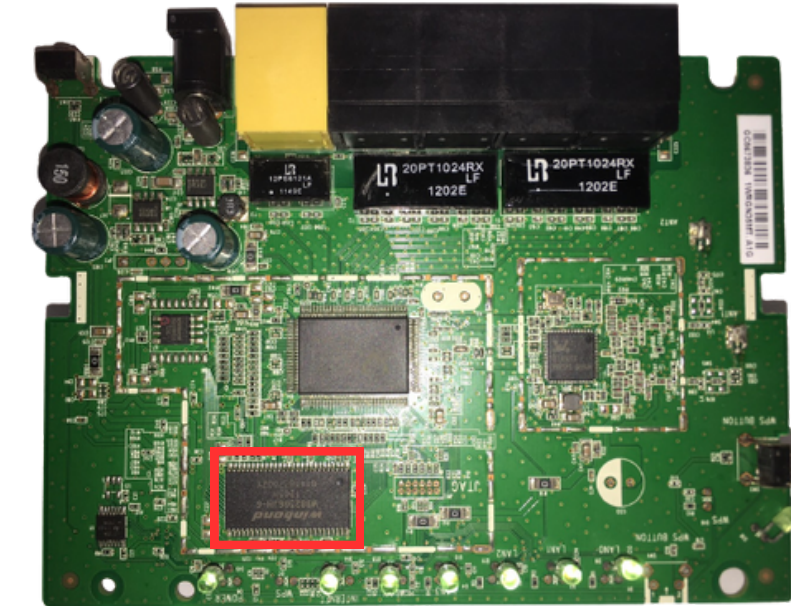
RTL8192CE

SINGLE-CHIP IEEE 802.11b/g/n
2T2R WLAN



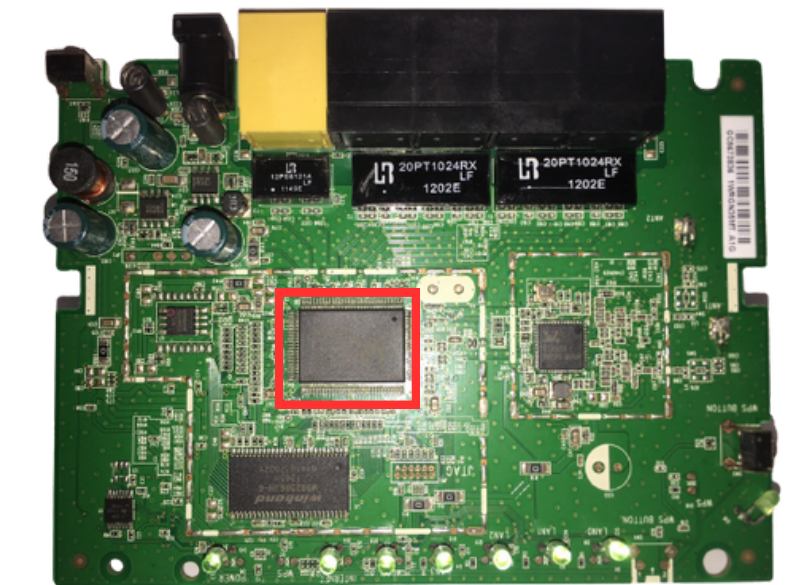
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4M X 4 BANKS X 16 BITS SDRAM



RTL8196C

Realtek provides the turnkey solution for 11n Router/AP in hardware and software.



Datasheet

RT8292AHZSP

Power-up & Measurement Procedure

1. Apply a 12V nominal input power supply ($4.5V < V_{IN} < 23V$) to the VIN and GND terminals.
2. The EN voltage is pulled to logic high by R4 (100kΩ to VIN) to enable operation. Drive EN high (>2.7V) to enable operation or low (<0.4V) to disable operation.
3. Verify the output voltage (approximately 3.3V) between VOUT and GND.
4. Connect an external load up to 2A to the VOUT and GND terminals and verify the output voltage and current.

Output Voltage Setting

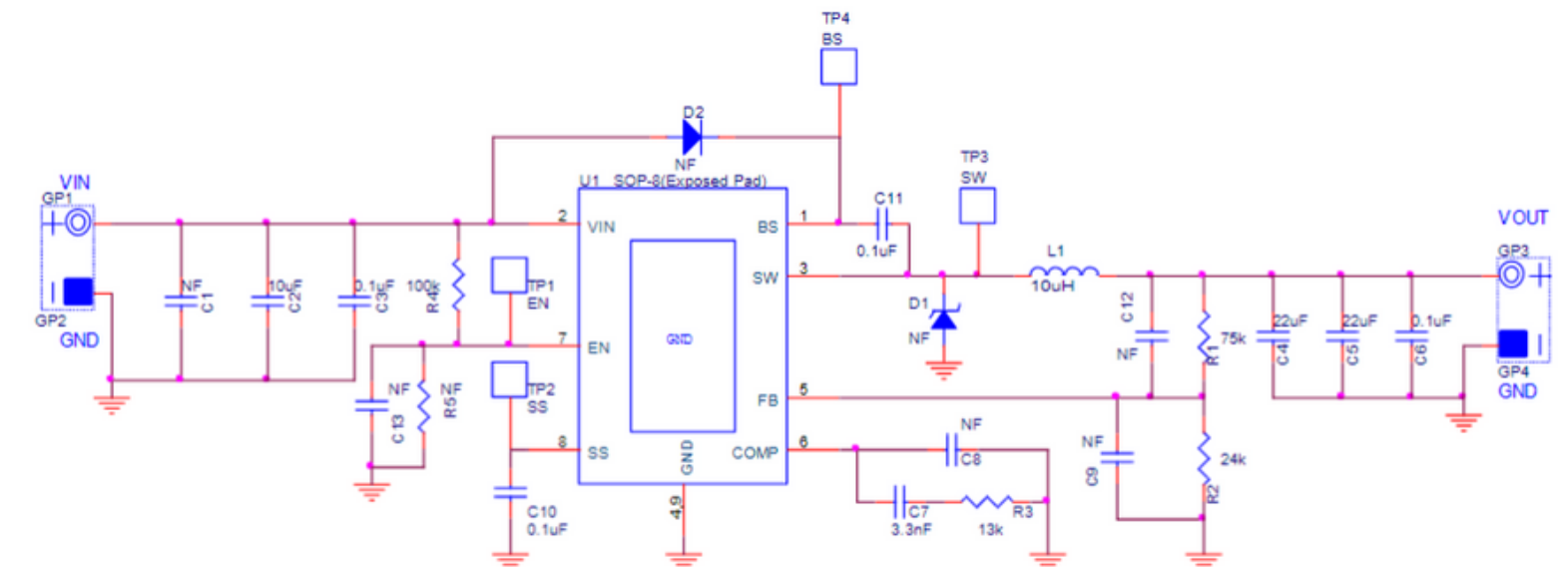
Set the output voltage with the resistive divider (R1, R2) between VOUT and GND with the midpoint connected to FB. The output is set by the following formula:

$$V_{OUT} = 0.8 \times \left(1 + \frac{R1}{R2}\right)$$

The installed VOUT capacitors (C4, C5) are 22μF, 16V X5R ceramic types. Do not exceed their operating voltage range and consider their voltage coefficient (capacitance vs. bias voltage) and ensure that the capacitance is sufficient to maintain stability and provide sufficient transient response for your application. This can be verified by checking the output transient response as described in the RT8292 IC datasheet.

Key features	Evaluation board number: PCB004_V1
Default Input Voltage	12V
Max Output Current	2A
Default Output Voltage	3.3V
Default Marking & Package Type	RT8292AHZSP, PSOP-8 (Exposed Pad)
Operation Frequency	Steady 340kHz at all load currents
Other Key Features	4.5V to 23V Input Voltage Range Programmable Soft-Start
Protection	Output Under-Voltage Protection (hiccup mode): Cycle-by-cycle Current Limit Thermal Shutdown

EVB Schematic Diagram

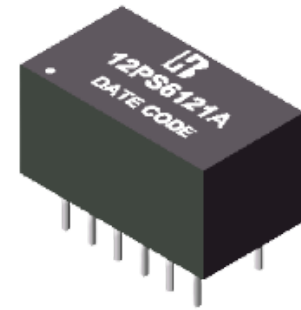


C2: 10μF/50V/X5R, 1206, TDK C3216X5R1H106K

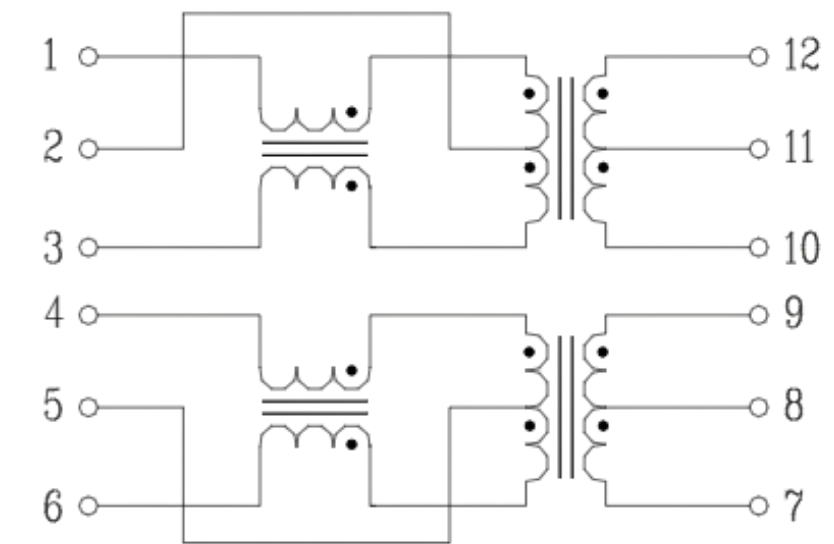
C4, C5: 22μF/16V/X5R, 1210, Murata GRM32ER61C226K

L1: 10μH TAIYO YUDEN NR8040T100M, DCR=34mΩ

12PS6121A

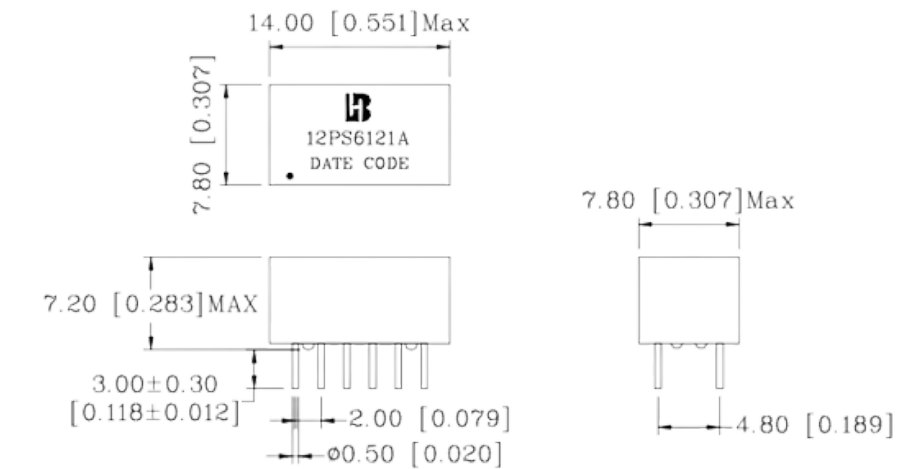


- Designed to meet IEEE 802.3u requirement, including 350uH OCL with 8mA bias.
- Operating temperature range: 0°C to +70°C.
- Storage temperature range: -25°C to +125°C.



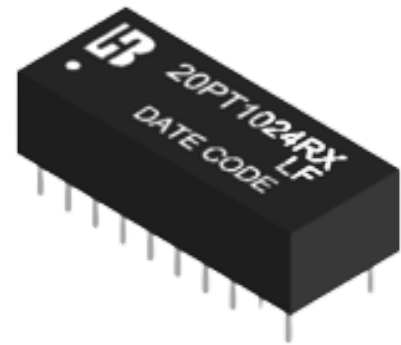
Electrical Specifications @ 25°C										
Part Number	Turns Ratio (±3%)	OCL (uH Min) @ 100KHz/0.1V with 8mA DC Bias	C _{WV} (pF Max)	L.L (uH Max)	DCR (Ω Max)		HI-POT (Vrms)			
					1-3/4-6	12-10/9-7				
12PS6121A	1CT:1CT	350	28	0.5	1.1	0.9	1500			

Continue										
Part Number	Insertion Loss (dB Max)	Return Loss (dB Min)				Cross talk (dB Min)		DCMR (dB Min)		
		0.3-100MHz	0.3-30MHz	40MHz	50MHz	60-80MHz	0.3-60MHz	60-100MHz	30MHz	60MHz
12PS6121A	-1.1	-18	-15.5	-13	-12	-45	-35	-40	-35	-30



Units: mm [Inches] Tolerances: xx.x0 ± 0.25 [0.010]
0.xx ± 0.05 [0.002]

20PT1024RX-LF



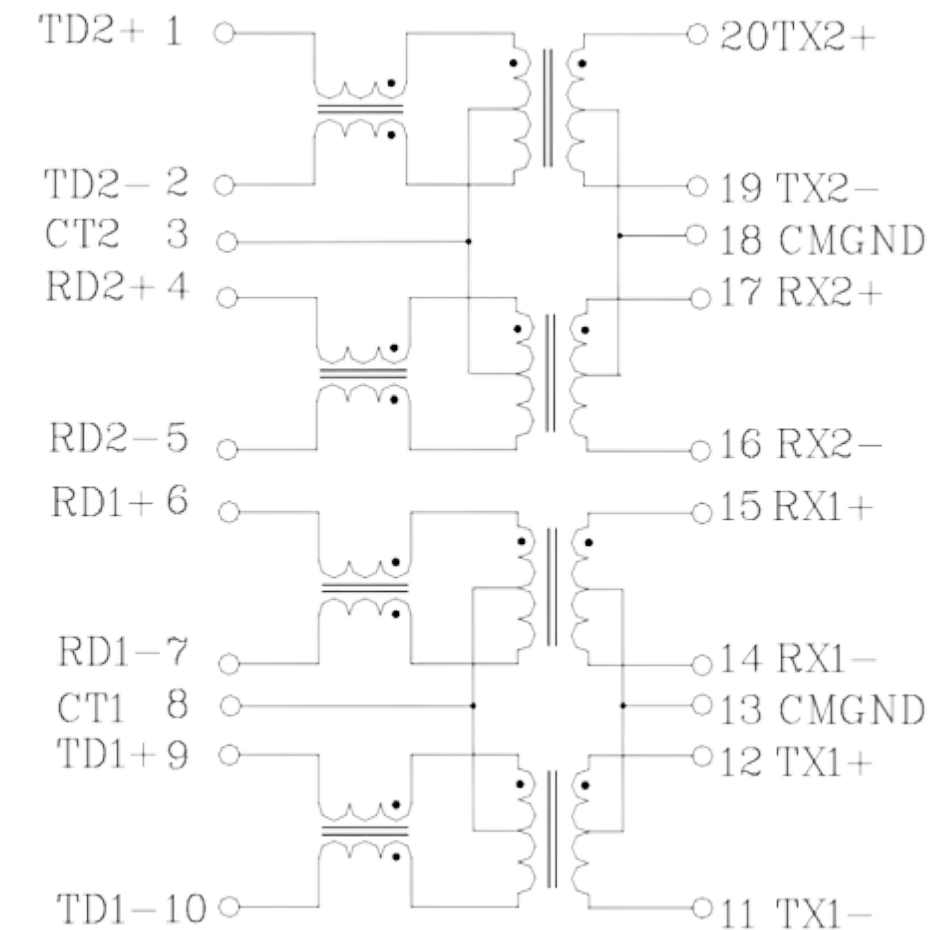
- Compliant with IEEE 802.3u and ANSI X3.263 standards including 350uH OCL with 8mA Bias.
- Symmetrical TX and RX channels for Auto MDI/MDIX capability.
- Compliance with ROHS requirements.
- Operating temperature range : 0°C to +70°C.
- Storage temperature range: -25°C to +85°C.

Electrical Specifications @ 25°C

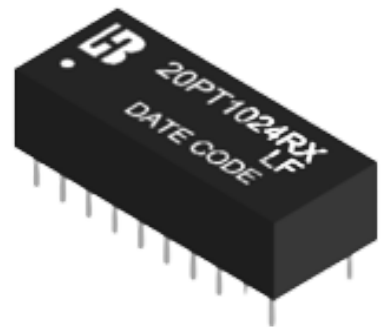
Part Number	Turns Ratio (±5%)		OCL (μH Min) @100KHz/0.1Vrms with 8mA DC/Bias	C _{ww} (pF Max)	DCR (Ω Max)	HI-POT (Vrms)
	TX	RX				
20PT1024RX LF	1CT:1CT	1CT:1CT	350	56	0.9	1500

Continue

Part	Insertion Loss (dB Max)	Return Loss (dB Min)				Cross talk (dB Min)	DCMR (dB Min)
		0.3-100MHz	0.3-30MHz	30-60MHz	60-80MHz		
20PT1024RX LF	-1.1	-18	-14	-12	-35	-30	



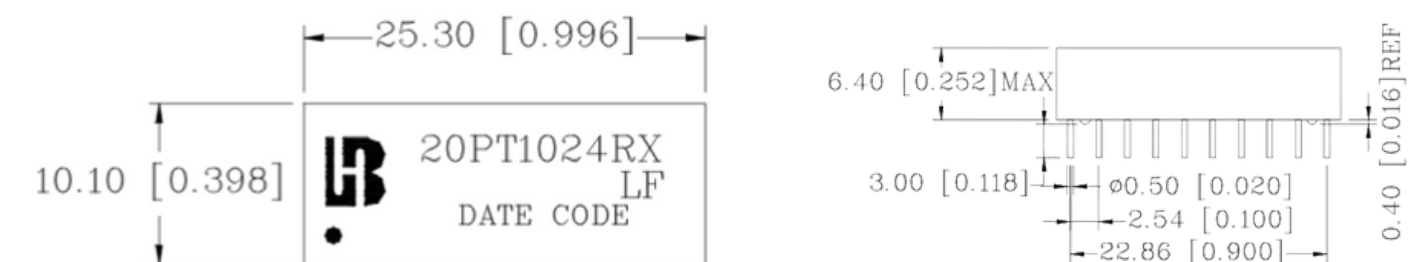
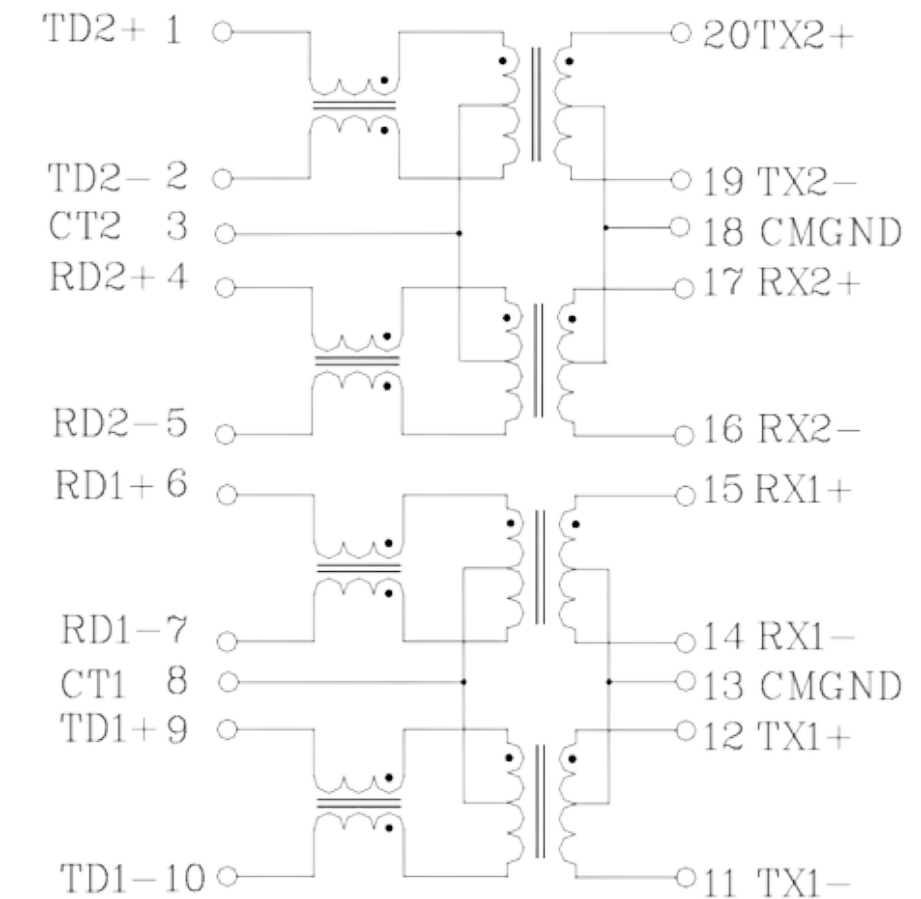
W9825G6JH



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Continue						
Part	Insertion Loss (dB Max)	Return Loss (dB Min)			Cross talk (dB Min)	DCMR (dB Min)
		0.3-30MHz	30-60MHz	60-80MHz		
20PT1024RX LF	-1.1	-18	-14	-12	-35	-30

Continue						
Part	Insertion Loss (dB Max)	Return Loss (dB Min)			Cross talk (dB Min)	DCMR (dB Min)
		0.3-30MHz	30-60MHz	60-80MHz		
20PT1024RX LF	-1.1	-18	-14	-12	-35	-30



Experience & Lessons

Ensure safety during disassembly

Follow safe disassembly procedures to avoid the danger of retained charge in internal capacitors.

Observing circuit board knowledge

We observed that the traces on the circuit board do not follow right angles, which is different from what we imagined. However, upon investigation, we learned that this is to ensure impedance matching and to avoid the accumulation of heat at right angles. Therefore, most of the traces are designed using curves or 45° angles.

We utilized datasheets to understand component information.

The components on the circuit board are diverse, but through this disassembly, we learned to look up information about parts, including basic operating voltage and power consumption. The datasheet also provides detailed information about the names and functions of each pin.



Literature Reference

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<https://pdf1.alldatasheet.com/datasheet-pdf/view/862415/BOTHHAND/20PT1024RX-LF.html>